

# TECHNICAL DATA SHEET

SLIDE®

#470

## Purge-Atory Purging Compound

### PURGE-ATORY Purging Compound 470-45, 470-1000

#### Product Description

Purge-Atory is a revolutionary heavy-duty purging compound. Recommended for use with gas emitting resins such as Delrin® and acetal. Requires no mixing or preparation time. Formulated with a SAN resin carrier, Purge-Atory purging compound is safe to purge right through the mold, saving time, material and money. All ingredients are GRAS rated so it is safe to use for food packaging applications. For use with injection molding, extrusion and blow molding.

#### Applications

Purging Compound

#### Unit Package Description

48 and 1,100 pound boxes

#### Generic Description

Purging Compound

#### Net Weight Fill

45 & 1,000 pounds

#### UPC Code

858799000707

#### Appearance

Resin Pellet

#### Odor

None

#### Flash Point F

>750 degrees

#### Flash Point C

>400 degrees

#### Base Type

Resin

#### Evaporation Rate

N/A

#### HMIS Rating

0, 0, 0, None

#### DOT Proper Shipping Name

Not regulated, Granules, NOI

#### Removal

N/A

#### Units Per Case

45 & 1,000 pounds

#### Case Weight (lbs)

45 / 1,000

#### Working Temperature F

370 to 610 degrees

#### Working Temperature C

187 to 321 degrees

#### Propellant

N/A

#### NFPA Aerosol Flammability Level

N/A

